

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







DB2440400L

# **Panasonic**

## DB2440400L

## Silicon epitaxial planar type

### For rectification

#### ■ Features

- · Small reverse current IR
- Forward current (Average) IF(AV) = 3 A rectification is possible
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: A8

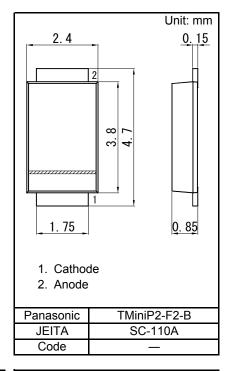
Established: 2011-02-01

: 2013-04-19

Revised

#### ■ Packaging

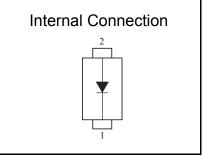
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



### ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit				
Reverse voltage	VR	40	V				
Repetitive peak reverse voltage	VRRM	40	V				
Forward current (Average)*1	IF(AV)	3.0	Α				
Non-repetitive peak forward surge current *2	IFSM	60	Α				
Junction temperature	Tj	125	°C				
Operating ambient temperature	Topr	-40 to +85	°C				
Storage temperature	Tstg	-40 to +125	°C				

Note: \*1 For embedded alumina substrate (substrate size: 5 cm× 5 cm)



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<sup>\*2 50</sup> Hz sine wave 1 cycle (Non-repetitive peak current)

### DB2440400L

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### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

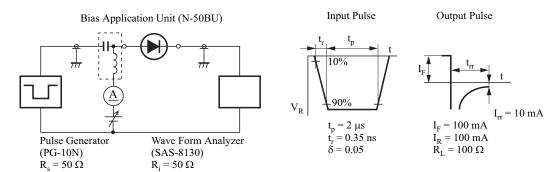
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 3.0 A			0.53	V
Reverse current	IR	VR = 40 V			50	μΑ
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		85		pF
Reverse recovery time *1	trr	IF = IR = 100 mA Irr = 10 mA, RL = 100 $\Omega$		30		ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*1 trr test circuit

Established: 2011-02-01

: 2013-04-19

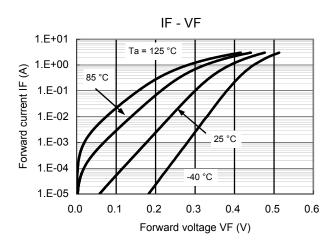
Revised

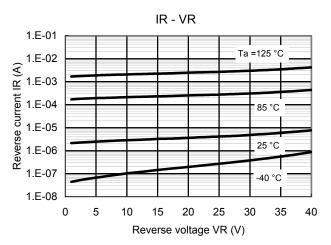


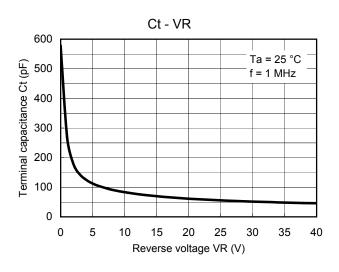
DB2440400L

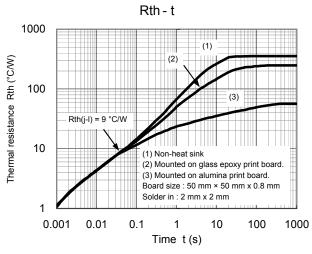
# **Panasonic**

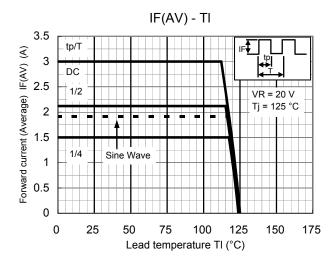
## Technical Data (reference)

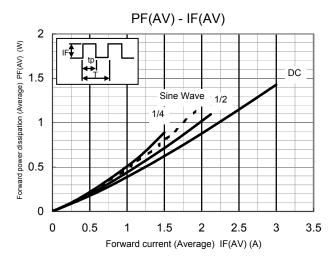












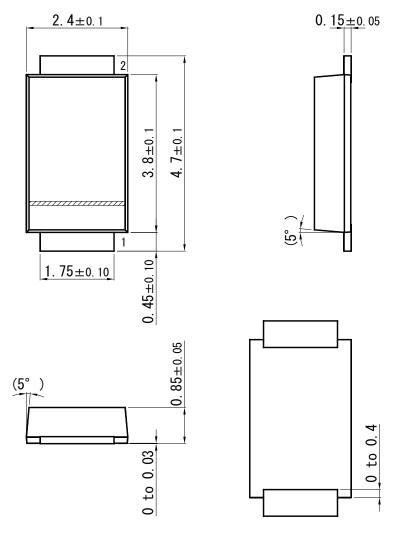
Established: 2011-02-01 Revised: 2013-04-19

DB2440400L

# **Panasonic**

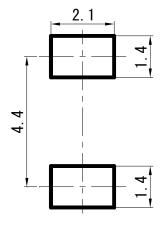
TMiniP2-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)

Established: 2011-02-01 Revised: 2013-04-19



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